



Docket No.: M4065.0196/P196  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Shane P. Leiphart

Application No.: 09/371,955  
Confirmation No.: 9847

Filed: August 11, 1999

Group Art Unit: 2811

For: ENHANCED BARRIER LINER  
FORMATION FOR VIAS

Examiner: Donghee Kang

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AMENDMENT

Box Non-Fee Amendment  
Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In response to the Office Action dated January 2, 2002 (Paper No. 13), please amend the above-identified U.S. Patent application as follows:

In the Claims:

Please cancel claims 1-25 without prejudice to their underlying subject matter.

Subt D Please replace the claims with the respective amended claims below:

26. (Three Times Amended) A semiconductor device, comprising:

a metallic layer over a substrate;

a dielectric layer over said metallic layer;

a via hole extending through the dielectric layer to a surface of the metallic layer;